

Specification for Approval

Date: 2018/06/15

Customer: 深圳台慶

	TAI-TECH P/N:	TMPC0402HPV-Se	ries(G)-Z02
	CUSTOMER P/N:		
	DESCRIPTION:		
	QUANTITY:	pcs	3
REM	IARK:		
	Cu	stomer Approval Feedba	ack

□西北臺慶科技股份有限公司

TAI-TECH Advanced Electronics Co., Ltd <u>Headquarter:</u>

NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN HSIEN, TAIWAN, R.O.C.

TEL: +886-3-4641148 FAX: +886-3-4643565

http://www.tai-tech.com.tw

E-mail: sales@tai-tech.com.tw

□Office:

深圳辦公室

11BC,Building B Fortune Plaza,NO.7002, Shennan Avenue, Futian

District Shenzhen

TEL: +86-755-23972371 FAX: +86-755-23972340

□臺慶精密電子(昆山)有限公司

TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA

TEL: +86-512-57619396 FAX: +86-512-57619688

E-mail: sales@tai-tech.cn

■慶邦電子元器件(泗洪)有限公司

TAIPAQ ELECTRONICS (SIHONG) CO., LTD JIN SHA JIANG ROAD, CONOMIC DEVELOPMENT ZONE SIHONG, JIANGSU, CHINA.

TEL: +86-527-88601191 FAX: +86-527-88601190

E-mail: sales@taipaq.cn

Sales Dep.

APPROVED	CHECKED
管哲頎	劉瑷瑄
Eric Kuan	Aries Liu

R&D Center

APPROVED	CHECKED	DRAWN	
羅宜春	梁周虎	許靜	

SMD Power Choke Coil

TMPC0402HPV-Series(G)-Z02

ECN HISTORY LIST								
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN			
1.0	18/06/15	新發行	羅宜春	梁周虎	許靜			
備								
註								

SMD Power Choke Coil

TMPC0402HPV-Series(G)-Z02

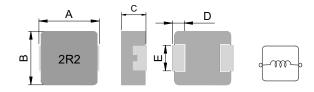
1. Features

- 1. Carbonyl powder inductor.
- 2. Compact design.
- 3. High current $\mbox{, low DCR}$, high efficiency.
- 4. Very low acoustic noise and very low leakage flux noise.
- 5. High reliability.
- 6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 7. High reliability -Reliability test meet AEC-Q200

2. Applications

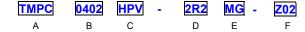
Note PC power system $\,^{,}$ incl. IMVP-6 DC/DC converter.

3. Dimensions



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPC0402HPV	4.45±0.25	4.06±0.25	1.8±0.2	0.76±0.30	2.0±0.20

4. Part Numbering



A: Series

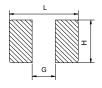
B: Dimension

C: Type H: Carbonyl powder; P: PAD broaden V=Vehicle.





Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)	
5.2	2.2	2.4	

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at
0.12mm and above.

5. Specification

Part Number	Inductance L0 (uH)±20% @ 0 A	I rms (A) Typ.	I sat (A) Typ.	DCR(mΩ) Typ.@25℃	DCR(mΩ) Max.@25℃
TMPC0402HPV-R10YG-Z02	0.10±30%	12	35	3.2	4.0
TMPC0402HPV-R18YG-Z02	0.18±30%	13.5	28	4.6	5.4
TMPC0402HPV-R22YG-Z02	0.22±30%	13	24	6.6	7.3
TMPC0402HPV-R33MG-Z02	0.33	10	18	7.8	8.6
TMPC0402HPV-R47MG-Z02	0.47	8.0	12	11.2	14
TMPC0402HPV-R56MG-Z02	0.56	7.3	10	13.5	16
TMPC0402HPV-R68MG-Z02	0.68	7	10	16	19
TMPC0402HPV-1R0MG-Z02	1.00	5.0	8.5	22	27
TMPC0402HPV-1R2MG-Z02	1.20	4.8	7.8	25	30
TMPC0402HPV-1R5MG-Z02	1.50	4.5	7.0	34.8	42
TMPC0402HPV-2R2MG-Z02	2.20	4.0	6.0	51	61
TMPC0402HPV-3R3MG-Z02	3.30	3.5	4.0	69	76
TMPC0402HPV-4R7MG-Z02	4.70	2.6	3.5	95	105
TMPC0402HPV-5R6MG-Z02	5.60	2.2	3.0	112	125
TMPC0402HPV-6R8MG-Z02	6.80	2.1	2.8	150	172
TMPC0402HPV-8R2MG-Z02	8.20	2.0	2.5	158	180
TMPC0402HPV-100MG-Z02	10.0	1.8	2.3	215	243
TMPC0402HPV-150MG-Z02	15.0	1.5	1.9	325	374
TMPC0402HPV-220MG-Z02	22.0	1.2	1.4	470	500

Note:

- 1. Test frequency : L/Q : 100KHz /1.0V;
- 2. All test data referenced to 25 $^{\circ}\!\mathbb{C}\,$ ambient.
- 3. Testing Instrument: L: HP4284A,CH11025,CH3302,CH1320 ,CH1320 S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
- 4. Heat Rated Current (Irms) will cause the coil temperature rise approximately $\,\Delta t$ of 40 $^{\circ}\! C$
- 5. Saturation Current (Isat) will cause L0 $\,$ to drop approximately 20% $\,$
- 6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 7. Special inquiries besides the above common used types can be met on your requirement.

6. Material List



NO	Items	Materials	
1	Core	Carbonyl Powder.	
2	Wire	Polyester Wire or equivalent.	
3	Clip	100% Pb free solder(Ni+SnPlating)	
4	paint	Epoxy resin	
5	Ink	Halogen-free ketone	

7. Reliability and Test Condition

Item	Performance	Test Condition				
Operating temperature	-55~+125°C (Including self - temperature rise)					
Storage temperature and Humidity range	110~+40°ℂ,50~60%RH (Product with taping) 255~+125°ℂ (on board)					
Electrical Performance Test						
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.				
DCR	Refer to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.				
Saturation Current (Isat)	Approximately △L20%	Saturation DC Current (Isat) will cause L0 to drop △L(%)				
Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise \triangle T(\mathbb{C}). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer				
Reliability Test						
High Temperature Exposure(Storage) AEC-Q200 Temperature Cycling AEC-Q200	-	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Temperature: 125±2°C (Inductor) Duration: 1000hrs Min. Measured at room temperature after placing for 24±2 hrs Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -55±2°C 30min Min.(Inductor) Step2: 125±2°C 30min Min. Step3: 125±2°C 30min Min. Step4: Low temp. transition time 1min MAX. Number of cycles: 1000 Measured at room temperature after placing for 24±2 hrs				
Moisture Resistance	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1.Baked at50 ℃ for 25hrs, measured at room temperature afte placing for 4 hrs. 2.Raise temperature to 65±2 ℃ 90-100 %RH in 2.5hrs, and keep 3 hours, cool down to 25 ℃ in 2.5hrs. 3.Raise temperature to 65±2 ℃ 90-100 %RH in 2.5hrs, and keep 3 hours, cool down to 25 ℃ in 2.5hrs, keep at 25 ℃ for 2hrs then keep at -10 ℃ for 3hrs 4.Keep at 25 ℃ 80-100 %RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1-2 hrs.				
Biased Humidity (AEC-Q200)		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±3% R.H, Temperature: 85°C±2°C Duration: 1000hrs Min with 100% rated current. Measured at room temperature after placing for24±2hrs				
High Temperature Operational Life (AEC-Q200)		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Temperature : 125±2°C (Inductor) Duration : 1000hrs Min. with 100% rated current. Measured at room temperature after placing for24±2hrs				
External Visual	Appearance : No damage.	Inspect device construction, marking and workmanship. Electrical Test not required.				
Physical Dimension		According to the product specification size measurement				
Resistance to Solvents	Appearance : No damage.	Add aqueous wash chemical - OKEM clean or equivalent.				
Mechanical Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Form change (Vi)ft/sec SMD 100 6 Half-sine 12.3 Lead 100 6 Half-sine 12.3 shocks in each direction along 3 perpendicular axes.				

Item	Performance	Test Condition				
Vibration		IPC/JEDEC J-STD-020DClassification Reflow Profiles Oscillation Frequency: 10∼2K∼10Hz for 20 minute Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations) ∘ Test condition:				
Resistance to Soldering Heat	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the	Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate 260±5(solder 10±1 25mm/s ±6 mm/s 1				
Thermal shock (AEC-Q200)	specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -55±2℃ 15±1min(Inductor) Step2: 125±2℃ thinin 20Sec. Step3: 125±2℃ 15±1min Number of cycles: 300 Measured at room fempraturc after placing fo24±2hrs				
ESD	Appearance : No damage.	ID A SOUND TURNO (INS)				
Solderability	More than 95% of the terminal electrode should be covered with solder \circ	Steam Aging: 16 hours ± 15 min Preheat: 150°C,60sec. Solder: Sn96.5% Ag3% Cu0. 5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5% Dip time: 4±1sec. Depth: completely cover the termination				
Electrical Characterization	Refer Specification for Approval	Summary to show Min, Max, Mean and Standard deviation .				
Flammability	Electrical Test not required.	V-0 or V-1 are acceptable.				
Board Flex	Appearance : No damage	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board. Support Solder Chip Printed circuit board before testing				
		Printed circuit board under test Displacement Displacement				
Terminal Strength(SMD)	Appearance : No damage	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. **radius 0.5 mm** DUT **wide** **wide** **thickness**				
		shear force				

Note: When there are questions concerning measurement result: measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(2) Solder re-flow:

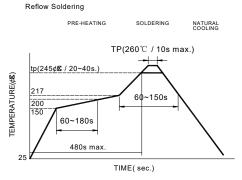
Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

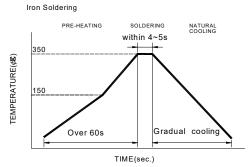
- \bullet Preheat circuit and products to 150 $\!\!\!\!\!\!^{\circ}_{\circ}$
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm

- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.



Reflow times: 3 times max.

Fig.1

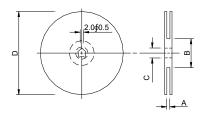


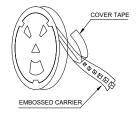
Iron Soldering times: 1 times max.

Fig.2

9. Packaging Information

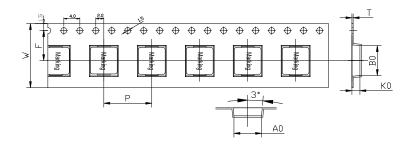
(1) Reel Dimension





		B(mm)	C(mm)	D(mm)
13"x12mm	12.4+2/-0	100±2	13+0.5/-0.2	330

(2) Tape Dimension

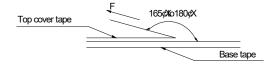


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)
TMPC	0402	5.0±0.1	4.4±0.1	2.3±0.1	8.0±0.1	12±0.3	5.5±0.1	0.35±0.05

(3) Packaging Quantity

ТМРС	0402	
Chip / Reel	3000	
Inner box	6000	
Carton	24000	

(4) Tearing Off Force



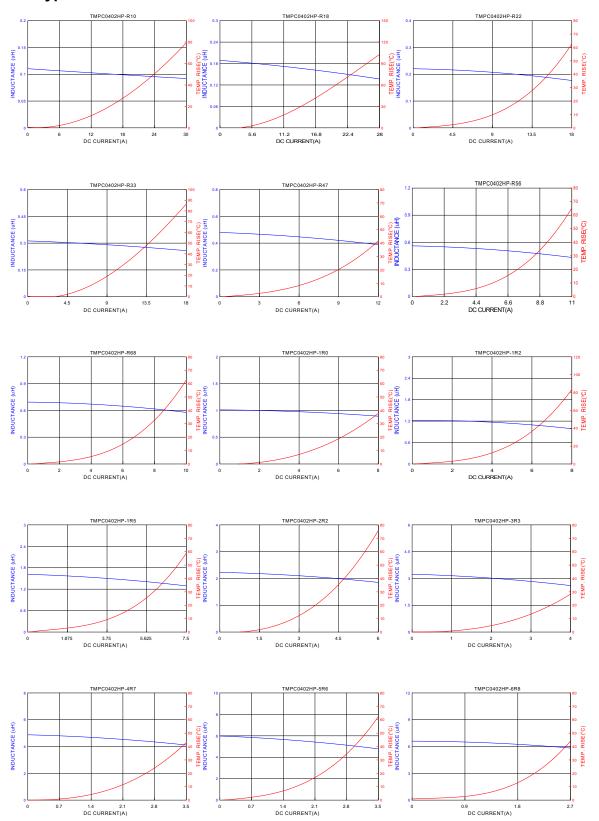
The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 standard).

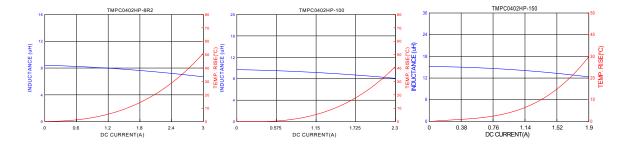
Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	

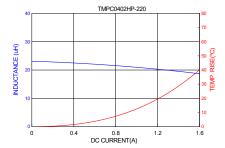
Application Notice

- Storage Conditions(component level)
- To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

10. Typical Performance Curves







单击下面可查看定价,库存,交付和生命周期等信息

>>TAI-TECH(台庆)